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No. 0174 P. 1

Application No. 10632,550
Attorney Docket: CPAC 1017-7.DS

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Signed:

Paula Frank Shirley

In THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Marcos Kamezus	Attorney Docket No.: CPAC 1017-7.DS
Application No.: 10/632,550	Examiner: Mai-Huong Tran
Dated: 02 August 2003	Group: 2811
Title: Semiconductor Multi-Package Module Including Stacked-Die Package And Having Wire Bond Interconnect Between Stacked Packages	Confirmation No.: 2570
	Customer No. 22470

INFORMATION DISCLOSURE STATEMENT AFTER ALLOWANCE

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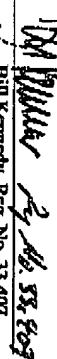
Sir:

Applicants submit the below-listed documents to be placed in the file:

- Takahashi et al., U. S. Patent No. 6,025,648 issued 15 February 2000 for "Shock Resistant Semiconductor Device and Method for Producing Same".

Respectfully submitted,
Haynes, Belfel & Wolfson LLP

Date: 11 May 2005

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